
maXTouch 2911-node Touchscreen Controller Product Brief

Description

The mXT2952TD 1.0 uses a unique charge-transfer acquisition engine to implement Microchip's patented capacitive sensing method. Coupled with a state-of-the-art CPU, the entire touchscreen sensing solution can measure, classify and track a number of individual finger touches with a high degree of accuracy in the shortest response time. The mXT2952TD 1.0 allows for both mutual and self capacitance measurements, with the self capacitance measurements being used to augment the mutual capacitance measurements to produce reliable touch information.

maXTouch® Adaptive Sensing Touchscreen Technology

- Up to 41 X (transmit) lines and 71 Y (receive) lines for use by touchscreen and keys
- Touchscreen size 21 inches (16:9 aspect ratio), assuming a sensor electrode pitch of 6.5 mm. Other sizes are possible with different electrode pitches and appropriate sensor material
- A maximum of 2911 X/Y nodes can be allocated to the touch sensor
- Multiple touch support with up to 16 concurrent touches tracked in real time
- HID Mouse mode reporting of single touches to the host, subject to configuration
- Dual-boot OS support for Microsoft® Windows® and Android™

Keys

- Up to 32 nodes can be allocated as mutual capacitance sensor keys (subject to other configurations)
- Adjacent Key Suppression (AKS) technology is supported for false key touch prevention

Touch Sensor Technology

- Discrete/out-cell support including glass and PET film-based sensors
- On-cell/touch-on display support including TFT, IPS and OLED
- Synchronization with display refresh timing capability
- Support for standard (for example, Diamond) and proprietary sensor patterns (review of designs by Microchip or a Microchip-qualified touch sensor module partner is recommended)

Front Panel Material

- Works with PET or glass, including curved profiles (configuration and stack-up to be approved by Microchip or a Microchip-qualified touch sensor module partner)
- 10 mm glass (or 5 mm PMMA) with bare finger (dependent on screen size, touch size, configuration and stack-up)
- 6 mm glass (or 3 mm PMMA) with multi-finger 5 mm glove (2.7 mm PMMA equivalent) (dependent on screen size, touch size, configuration and stack-up)

Touch Performance

- Moisture/Water Compensation
 - No false touch with condensation or water drop up to 22 mm diameter
 - One-finger tracking with condensation or water drop up to 22 mm diameter
- Mutual capacitance and self capacitance measurements supported for robust touch detection
- P2P mutual capacitance measurements supported for extra sensitive multi-touch sensing
- Noise suppression technology to combat ambient, charger, and power-line noise
 - Up to 240 V_{PP} between 1 Hz and 1 kHz sinusoidal waveform
 - Up to 20 V_{PP} between 1 kHz and 1 MHz sinusoidal waveform
- Stylus Support
 - Supports passive stylus with 1.5 mm contact diameter, subject to configuration, stack-up, and sensor design
- Burst Frequency
 - Flexible and dynamic Tx burst frequency selection to reduce EMC disturbance
 - Configurable Tx waveform shaping to reduce emissions

- Scan Speed
 - Up to 112 Hz report rate for one finger (subject to configuration)
 - Typical report rate for 10 touches ≥ 100 Hz (subject to configuration)
 - Initial touch latency < 14 ms for first touch from idle (subject to configuration)
 - Configurable to allow for power and speed optimization
- Touch panel failure detection
 - Automatic touch sensor diagnostics during run time to support the implementation of safety critical features
 - Diagnostics reported using dedicated output pin or by standard Object Protocol messages
 - Configurable test limits

On-chip Gestures

- Reports one-touch and two-touch gestures
- Supports wake up/unlock gestures, including symbol recognition

Enhanced Algorithms

- Lens bending algorithms to remove display noise
- Touch suppression algorithms to remove unintentional large touches, such as palm
- Palm Recovery Algorithm for quick restoration to normal state

Power Saving

- Programmable timeout for automatic transition from Active to Idle state
- Pipelined analog sensing detection and digital processing to optimize system power efficiency

Application Interfaces

- I²C slave with support for Standard mode (up to 100 kHz), Fast mode (up to 400 kHz), Fast-mode Plus (up to 1 MHz), High Speed mode (up to 3.4 MHz)
- USB HID interface for Microsoft Windows 8.x and later versions
- HID-I²C interface for Microsoft Windows 8.x and later versions
- Interrupt to indicate when a message is available
- Additional SPI Debug Interface to read the raw data for tuning and debugging purposes

Power Supply

- Digital (Vdd) 3.3V nominal
- Digital I/O (VddIO) 1.8V to 3.3V (I²C mode), 3.3V (USB mode)
- Analog (AVdd) 3.3V nominal
- High voltage external X line drive (XVdd) up to 9.2V

Package

- 162-ball UFBGA 10 × 5 × 0.6 mm, 0.5 mm pitch

Operating Temperature

- -40°C to $+85^{\circ}\text{C}$

PIN CONFIGURATION

0.1 162-ball UFBGA

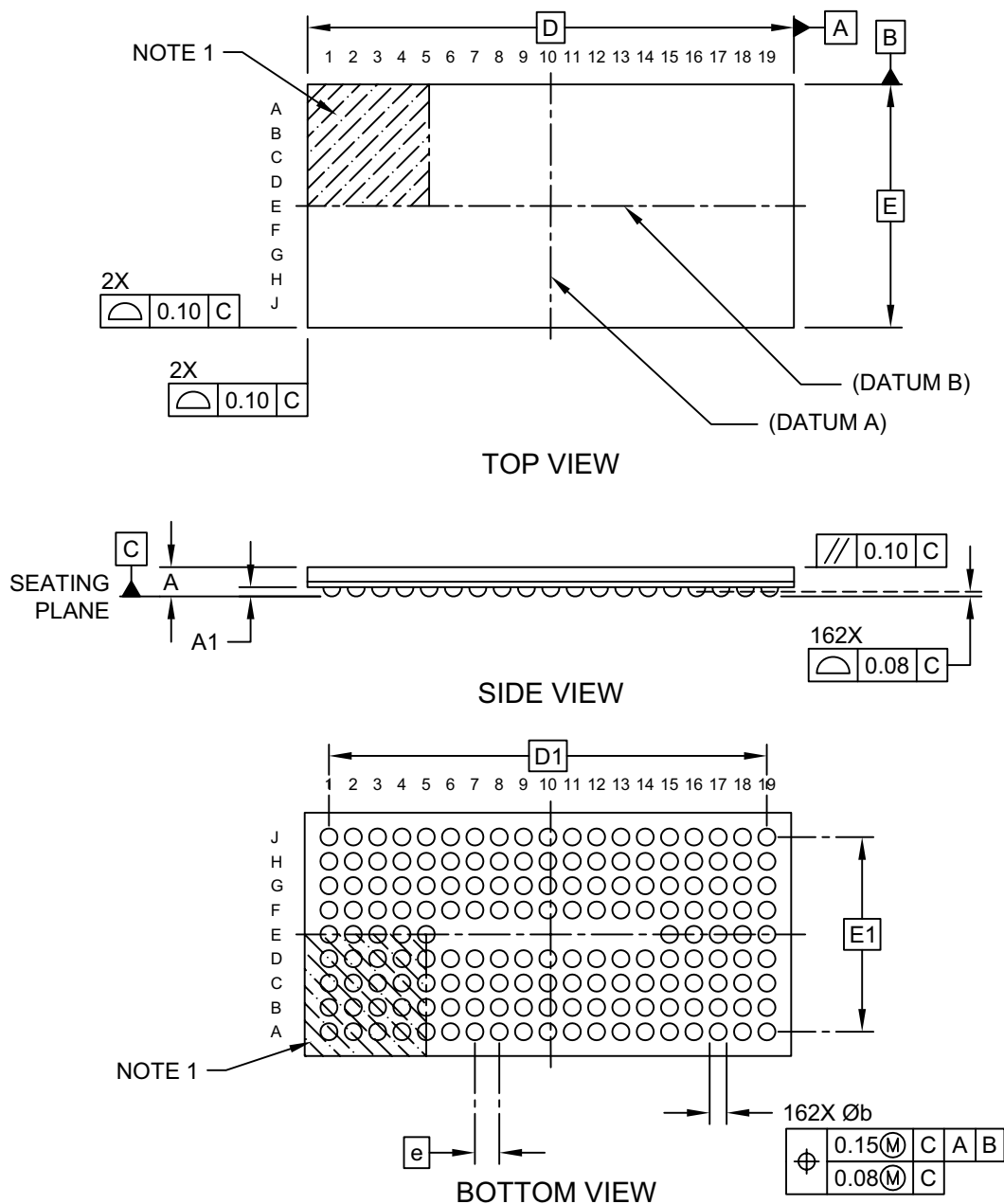
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19
A	☐ SCL	☐ <u>RESET</u>	☐ VDDIO	☐ DS0	☐ Y68	☐ Y64	☐ Y60	☐ AVDD	☐ GND	☐ Y50	☐ Y46	☐ Y42	☐ AVDD	☐ GND	☐ X38	☐ X39	☐ X40	☐ RESV	☐ RESV
B	☐ SDA	☐ USBDM	☐ GND	☐ Y70	☐ Y67	☐ Y63	☐ Y59	☐ Y56	☐ Y53	☐ Y49	☐ Y45	☐ Y41	☐ Y38	☐ VDDCORE	☐ X33	☐ X34	☐ X35	☐ X36	☐ X37
C	☐ ADDSEL USBDP	☐ COMMSEL	☐ AVDD	☐ Y69	☐ Y66	☐ Y62	☐ Y58	☐ Y55	☐ Y52	☐ Y48	☐ Y44	☐ Y40	☐ Y37	☐ GND	☐ X28	☐ X29	☐ X30	☐ X31	☐ X32
D	☐ I2CMODE	☐ NOISE_IN	☐ GND	☐ GND	☐ Y65	☐ Y61	☐ Y57	☐ Y54	☐ Y51	☐ Y47	☐ Y43	☐ Y39	☐ Y36	☐ XVDD	☐ X23	☐ X24	☐ X25	☐ X26	☐ X27
E	☐ <u>CHG</u>	☐ GPIO0 DBG_SS	☐ AVDD	☐ GND	☐ GND										☐ GND	☐ X19	☐ X20	☐ X21	☐ X22
F	☐ GPIO1	☐ GPIO2	☐ GND	☐ GND	☐ Y29	☐ Y25	☐ Y21	☐ Y18	☐ Y15	☐ Y11	☐ Y7	☐ Y3	☐ Y0	☐ XVDD	☐ X14	☐ X15	☐ X16	☐ X17	☐ X18
G	☐ GPIO3	☐ GPIO4 SYNC	☐ VDDIO	☐ Y33	☐ Y30	☐ Y26	☐ Y22	☐ Y19	☐ Y16	☐ Y12	☐ Y8	☐ Y4	☐ Y1	☐ GND	☐ X9	☐ X10	☐ X11	☐ X12	☐ X13
H	☐ GPIO5	☐ DBG_CLK XIN	☐ VDDIN	☐ Y34	☐ Y31	☐ Y27	☐ Y23	☐ Y20	☐ Y17	☐ Y13	☐ Y9	☐ Y5	☐ Y2	☐ XVDD	☐ X4	☐ X5	☐ X6	☐ X7	☐ X8
J	☐ DBG_DATA XOUT	☐ <u>TEST</u>	☐ VDDCORE	☐ Y35	☐ Y32	☐ Y28	☐ Y24	☐ AVDD	☐ GND	☐ Y14	☐ Y10	☐ Y6	☐ AVDD	☐ GND	☐ VREGBOOST	☐ X0	☐ X1	☐ X2	☐ X3

Top View

1.0 PACKAGING INFORMATION

162-Ball Ultra Thin Fine Pitch Ball Grid Array (C6B) - 10x5x0.6 mm Body [UFBGA] Atmel Legacy Global Package Code CAK

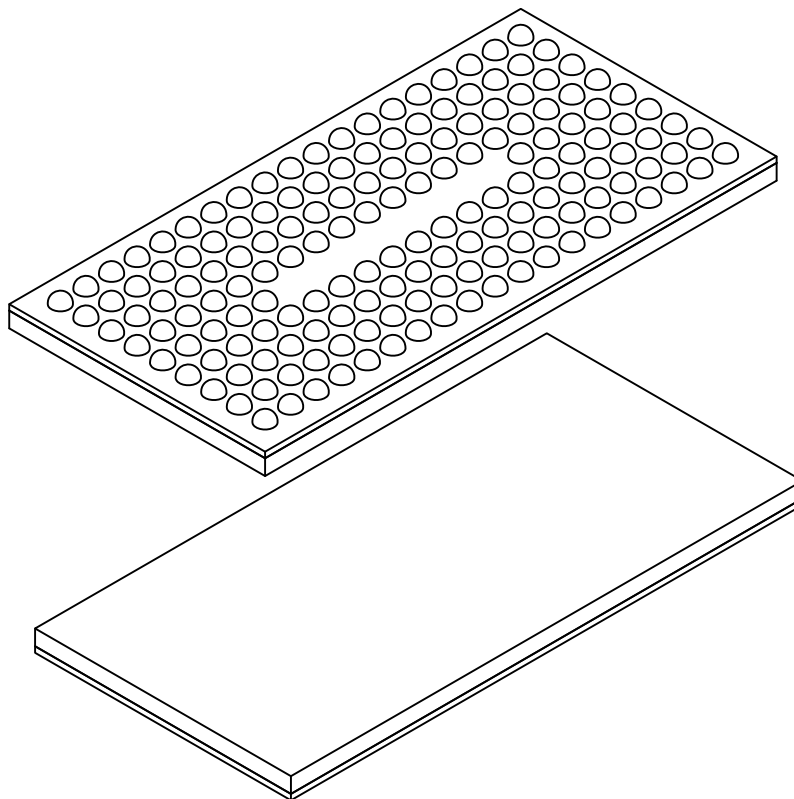
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-21167 Rev A Sheet 1 of 2

**162-Ball Ultra Thin Fine Pitch Ball Grid Array (C6B) - 10x5x0.6 mm Body [UFBGA]
Atmel Legacy Global Package Code CAK**

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	162		
Pitch	e	0.50 BSC		
Overall Height	A	0.488	0.546	0.60
Standoff	A1	0.120	0.155	0.190
Overall Length	D	10.00 BSC		
Overall Ball Spacing	D1	9.00 BSC		
Overall Width	E	5.00 BSC		
Exposed Pad Width	E1	4.00 BSC		
Ball Diameter	b	0.20	0.25	0.30

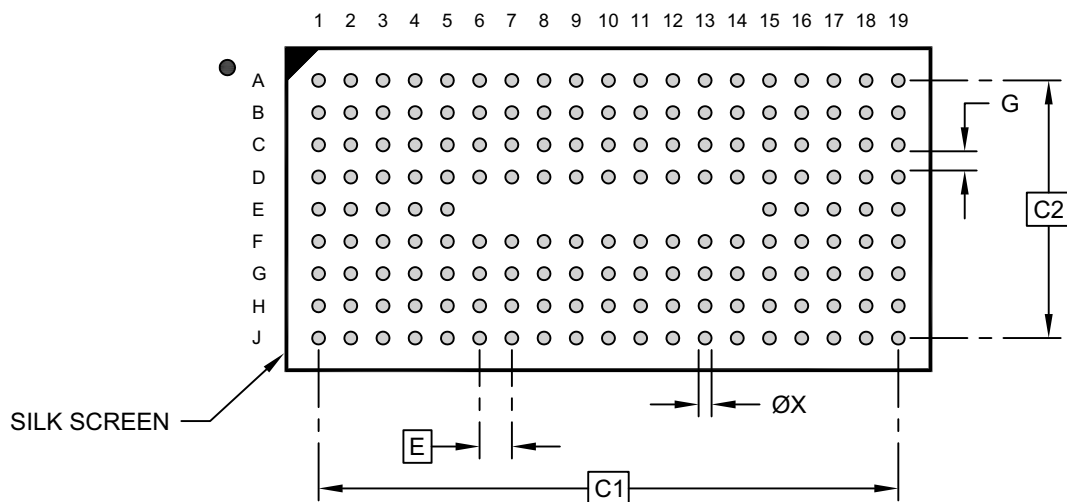
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-21167 Rev A Sheet 2 of 2

162-Ball Ultra Thin Fine Pitch Ball Grid Array (C6B) - 10x5x0.6 mm Body [UFBGA] Atmel Legacy Global Package Code CAK

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Contact Pad Spacing	C1	9.00 BSC		
Contact Pad Spacing	C2	4.00 BSC		
Contact Pad Diameter (X162)	X1			0.20
Contact Pad to Contact Pad	G	0.30		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

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APPENDIX A: REVISION HISTORY

Revision A (July 2019)

Initial edition for firmware revision 1.0.AA – Release

PRODUCT IDENTIFICATION SYSTEM

The table below gives details on the product identification system for maXTouch devices. See ["Orderable Part Numbers"](#) below for example part numbers for the mXT2952TD.

To order or obtain information, for example on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	-XXX	[X]	[X]	[XXX]
Device	Package	Temperature Range	Tape and Reel Option	Pattern

Device:

Base device name

Package:

A

=

QFP (Plastic Quad Flatpack)

CC

=

UFBGA (Ultra Thin Fine-pitch Ball Grid Array)

C2

=

UFBGA (Ultra Thin Fine-pitch Ball Grid Array)

NH

=

UFBGA (Ultra Thin Fine-pitch Ball Grid Array)

C4

=

X1FBGA (Extra Thin Fine-pitch Ball Grid Array)

MA

=

XQFN (Super Thin Quad Flat No Lead Sawn)

MA5

=

XQFN (Super Thin Quad Flat No Lead Sawn)

Temperature Range:

U

=

−40°C to +85°C (Grade 3)

T

=

−40°C to +85°C (Grade 3)

B

=

−40°C to +105°C (Grade 2)

Tape and Reel Option:

Blank

=

Standard Packaging (Tube or Tray)

R

=

Tape and Reel ⁽¹⁾

Pattern:

Extension, QTP, SQTP, Code or Special Requirements (Blank Otherwise)

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. See ["Orderable Part Numbers"](#) below or check with your Microchip Sales Office for package availability with the Tape and Reel option.

Orderable Part Numbers

Orderable Part Number	Firmware Revision	Description
ATMXT2952TD-C2U001 (Supplied in trays)	1.0.AA	162-ball UFBGA 10 × 5 × 0.6 mm, RoHS compliant Industrial grade; not suitable for automotive characterization
ATMXT2952TD-C2UR001 (Supplied in tape and reel)		

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as “unbreakable.”

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